SOD323 SILICON HIGH CURRENT SCHOTTKY BARRIER DIODE "SuperBAT"

FEATURES

- Low V_F SOD323 Cathode · High current capability • Miniature surface mount package Ν **APPLICATIONS** \succ • DC - DC converters Mobile telecomms
 - PCMCIA
 - **DEVICE MARKING**
 - Partmark detail BD

PINOUT - TOP VIEW



Partmark is for example only

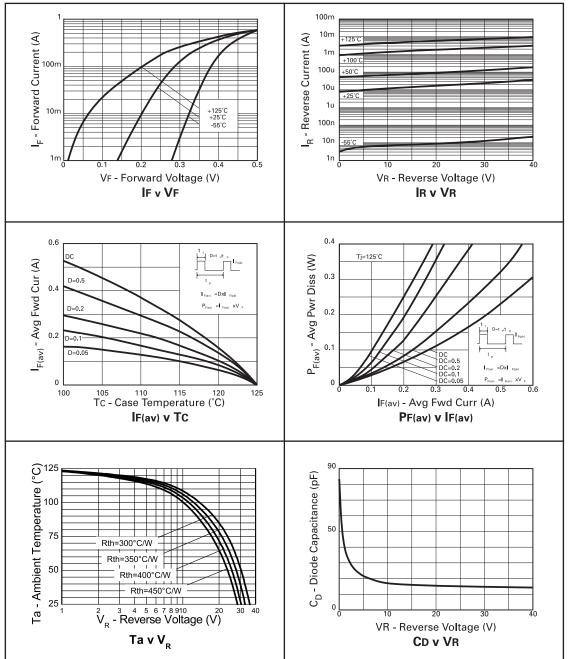
ABSOLUTE MAXIMUM RATINGS

PARAMETER		SYMBOL	VALUE	UNIT
Continuous Reverse Voltage		V _R	40	V
Forward Current (Continuous)		I _F	400	mA
Forward Voltage @ I _F =400mA		V _F	500	mV
Average Peak Forward Current; D.C.	= 50%	I _{FAV}	1000	mA
Non Repetitive Forward Current	t≤100µs t≤10ms	I _{FSM}	6.75 3	A A
Power Dissipation at T _{amb} =25°C		P _{tot}	250	mW
Storage Temperature Range		T _{stg}	-55 to +150	°C

ELECTRICAL CHARACTERISTICS (at $T_{amb} = 25^{\circ}C$ unless otherwise stated)

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
Reverse Breakdown Voltage	V _{(BR)R}	40	60		V	I _R =200μA
Forward Voltage	V _F		270 300 370 425 550 640 810 440	300 350 460 500 670 780 1050	mV mV mV mV mV mV mV	$I_{F}=50mA \\ I_{F}=100mA \\ I_{F}=250mA \\ I_{F}=400mA \\ I_{F}=750mA \\ I_{F}=1000mA \\ I_{F}=1500mA \\ I_{F}=500mA, T_{amb}=100^{\circ}C$
Reverse Current	I _R		15	40	μA	V _R =30V
Diode Capacitance	CD		20		pF	f=1MHz,V _R =25V

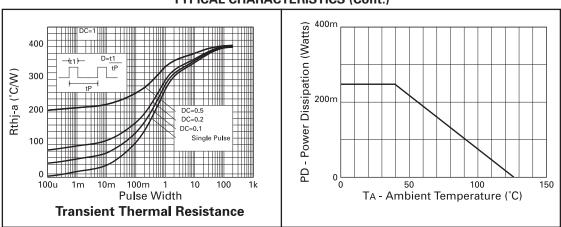




TYPICAL CHARACTERISTICS



Issue 5 - February 2008



TYPICAL CHARACTERISTICS (Cont.)



NOTES:



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"Preview"Future device intended for production at some point. Samples may be available

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"Not recommended for new designs"Device is still in production to support existing designs and production

"Obsolete"Production has been discontinued

Datasheet status key:

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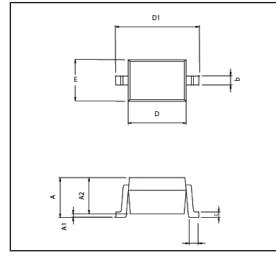
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PACKAGE OUTLINE



PACKAGE DIMENSIONS

DIM	Millimeters		DIM	Millimeters		
	Min	Мах	DIN	Min	Max	
А	-	1.150	D	1.520	1.800	
A1	0.000	0.100	D1	2.300	2.700	
A2	0.800	-	E	1.150	1.450	
b	0.250	0.400	L	0.100	0.400	
с	0.080	0.200	-	-	-	

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